

DuPont CB Series

Screen Printed Ink Materials for Printed Circuit Boards

Product Selection Guide

Product	Material	General Description	Benefits	Key Properties
CB028	Conductor	Silver conductor for EMI/RFI shielding on printed circuit boards or to fabricate low-voltage circuitry	<ul style="list-style-type: none">• Superior conductivity• Fine line printing capability• Excellent flexibility	5–10 mils (125–250 µm) printed line Sheet resistivity 7–10 (mΩ/sq/mil)
CB100	Via Plug	Silver providing high conductivity, plateable vias	<ul style="list-style-type: none">• High thermal conductivity• One part silver epoxy system• Reduction of processing steps	Sheet resistivity 3–5 (mΩ/sq/mil) 115 Tg (Celcius) 35 TCE (ppm) 8–26 mil via diameter
CB102	Via Plug	Solventless, high conductive silver via plug for plastic ball grid array (PBGA), buried via and sequential build-up board (SBU)	<ul style="list-style-type: none">• Solvent-less composition• Strong adhesion to copper and most laminate materials• High thermal conductivity	1.8 x 10.5 Ω/cm bulk resistivity 140 Tg (Celcius) 40 TCE (ppm) 6–18 mil via diameter
CB200	Conductor	Copper conductive material for EMI/RFI shielding on-board or to fabricate low-voltage circuitry	<ul style="list-style-type: none">• Conductivity comparable to silver• Strong adhesion to a wide variety of substrates• Excellent printing properties	Sheet resistivity 20–30 (mΩ/sq/mil)
CB230	Conductor	Silver coated copper solderable conductive material for enhanced solderability	<ul style="list-style-type: none">• Excellent solderability• Strong adhesion to a wide variety of substrates• Excellent printing properties• Excellent adhesion to aluminum	Sheet resistivity 65–75 (mΩ/sq/mil)
CB459	Conductor	Plateable silver conductor	<ul style="list-style-type: none">• Excellent adhesion• Solderable after plating	Specific resistance <5.0 (mΩ/cm)
CB500	Temporary Conductor	Silver conductor removable plating link for electroplating applications	<ul style="list-style-type: none">• Reduces process steps for selective electroplating applications• No residual ink on board after strip• Additive Process• Low temperature processing (<140°C)	Sheet resistivity 50–75 (mΩ/sq/mil)



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For more information on CB Series screen printed ink materials for printed circuit boards or other DuPont Microcircuit Materials products, please contact your local representative:

Americas

DuPont Microcircuit Materials
14 T.W. Alexander Drive
Research Triangle Park, NC 27709
Tel: 800.284.3382

Europe

DuPont (UK) Limited
Coldharbour Lane
Bristol BS16 1QD
United Kingdom
Tel: 44.117.931.3191

Asia

DuPont Kabushiki Kaisha
Sanno Park Tower, 11-1
Nagata-cho 2-chome
Chiyoda-ku, Tokyo 100-611
Japan
Tel: 81-3-5521-8650

DuPont Taiwan, Ltd.
45 Hsing-Pont Road
Taoyuan, Taiwan 330
Tel: 886-3-377-3616

DuPont China Holding Co. Ltd
Bldg 11, 399 Keyuan Rd.
Zhangji Hi-Tech Park
Pudong New District
Shanghai 201203, China
Tel: 86-21-6386-6366 ext. 2202

DuPont Korea Inc.
3~5th Floor, Asia tower #726
Yeoksam-dong, Gangnam-gu
Seoul 135-719, Korea
Tel: 82-10-6385-5399

E.I. DuPont India Private Limited
7th Floor, Tower C, DLF Cyber Greens
Sector-25A, DLF City, Phase-III
Gurgaon 122 002 Haryana, India
Tel: 91-124-4091818

DuPont Company (Singapore) Pte Ltd
1 Harbour Front Place, #11-01
Harbour Frong Tower One,
Singapore 098633
Tel: 65-6586-3022

<http://mcm.dupont.com>

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